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**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM 10038264	FILING DATE 01/03/2002	CLASS 403	SUBCLASS 270	GAU 3679	EXAMINER Garcia
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****APPLICANTS:** Park Seungbae; Sathe Sanjeev; Zubelewicz Aleksander;

**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A DIV OF 09/430,965 11/01/1999 PAT 6,347,901

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		EN999048C	
Verified and Acknowledged Examiner's initials <i>C. L.</i>			
TITLE : Solder interconnect techniques			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G	
ISSUE FEE			DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.
		Primary Examiner			
		PREPARED FOR ISSUE	Application Examiner		
<input type="checkbox"/> TERMINAL DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

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